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Cont.

44. (New) The tested semiconductor device of claim 43, wherein said process further comprises aligning tips of said probe elements with said corresponding electrical contact pads.

45. (New) The tested semiconductor device of claim 44, wherein said aligning tips of said probe elements includes altering an orientation of said probe substrate with respect to said probe card.

46. (New) The tested semiconductor device of claim 45, wherein said altering comprises moving a moveable element disposed so as to affect an orientation of said probe substrate with respect to said probe card.

47. (New) The tested semiconductor device of claim 44, wherein said aligning further comprises aligning said tips with an alignment plate.

48. (New) The tested semiconductor device of claim 43, wherein the process further comprises dicing said wafer to singulate said semiconductor devices.

49. (New) The tested semiconductor device of claim 43, wherein said probe substrate comprises a space transformer.

50. (New) A tested semiconductor device produced by a process comprising the steps of:  
providing a probe card comprising a plurality of electrical contacts;  
providing a probe substrate moveably fixed to said probe card and comprising a plurality of elongate, resilient probe elements, ones of said elongate resilient probe elements being in electrical communication with ones of said electrical contacts;  
aligning tips of said probe elements by altering an orientation of said probe substrate with respect to said probe card, said altering comprising moving a moveable element disposed so as to affect an orientation of said probe substrate with respect to said probe card;  
providing a semiconductor device;  
bringing said tips into contact with said semiconductor device; and

testing said semiconductor device.

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51. (New) The tested semiconductor device of claim 50, wherein said moveable element is threaded.

52. (New) The tested semiconductor device of claim 50, wherein said moveable element comprises a screw.

53. (New) The tested semiconductor device of claim 52, wherein said screw comprises a differential screw.

54. (New) The tested semiconductor device of claim 50, wherein moving said moveable element in a first direction causes at least a portion of said probe substrate to move toward said probe card.

55. (New) The tested semiconductor device of claim 54, wherein moving said moveable element in a second direction allows at least a portion of said probe substrate to move away from said probe card.

56. (New) The tested semiconductor device of claim 50, wherein said altering comprises actuating a servo mechanism disposed to alter a position of said probe substrate with respect to said probe card.

57. (New) The tested semiconductor device of claim 50, wherein said altering comprises actuating a piezoelectric actuator disposed to alter a position of said probe substrate with respect to said probe card.